

Amendments to the Specification:

Please replace the title with the following rewritten title:

INTERCONNECTION METHOD AND STRUCTURE

Please replace the paragraph [0012] with the following rewritten paragraph:

[0012] The features of the invention believed to be novel are set forth with particularity in the appended claims. The invention itself, however, both as to organization and method of operation, together with further objects and advantages thereof, may best be understood by reference to the following description taken in conjunction with the accompanying drawings, where like numerals represent like components, in which: ~~FIGs. 1 and 2 are sectional side and top views of a dielectric layer, a metallization pattern, an adhesive, and a cover sheet for use in accordance with one embodiment of the present invention.~~

Please add the following new paragraph after the paragraph [0012]:

[0012.1] **FIGs. 1 and 2** are sectional side and top views of a dielectric layer, a metallization pattern, an adhesive, and a cover sheet for use in accordance with one embodiment of the present invention..

Please replace the sub heading between paragraphs [0017] and [0018] with the following rewritten subheading:

Detailed Description of the Invention

Please replace the paragraph [0038] with the following rewritten paragraph:

[0038] After metallization pattern 42 142 and any optional additional layers or materials are applied, and dielectric layer 110 is removed over at least a portion of the active area of the at least one electrical device to result in the embodiment of **FIG. 12**. The localized removal of dielectric layer 110 can be done in any appropriate manner.